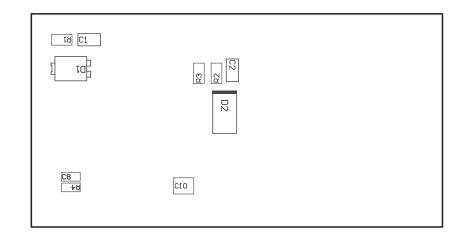


## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP40144	REV: E1	SUN REV	: Not In VersionControl		
	TID #: N/A					
PLOT NAME = Top Assembly Drawing	GENERATED : 9/13/2	017 8:18:40	PM	TEXAS INSTRUMENTS		



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP40144	REV: E1	SUN REU	: Not In VersionControl		
	TID #: N/A					
PLOT NAME = Bottom Assembly Drawing	GENERATED : 9/13/2	017 8:18:41	PM	TEXAS INSTRUMENTS		

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